Topics
1. Impurity and removal (Campbell p.21-22)
   Oxygen complex (Campbell, ref.12-20)
   Carbon complex (Campbell, ref.21, 22)
   Nitrogen effect (Campbell, ref.23-25)
2. CVD (chemical vapor deposition) (Campbell, ch.14)
   PECVD (plasma enhanced CVD)
   MOCVD (Metallorganic CVD)
3. MBE (molecular beam epitaxy)
4. Silicon oxynitrides (Campbell sec 4.7)
5. CVD oxide deposition
6. 4-point measurement (Campbell, sec 3.5, ref. 27)
7. High k materials for gate insulators (Campbell sec 4.8)
8. Doping by ion implantation (Campbell ch.5)
9. Projection printers (Campbell, 7.6)
10. Nanoimprint Lithography (Campbell, 9.11)
11. Ellipsometry
12. Extreme UV lithography (Campbell 9.5-7) (Alex Call)
13. Grow dielectric on GaAs
14. DMD printing (www. Intelligentmp.com, Campbell 19.9)
15. ZPAL printing (www. Lumarray.com)
16. 3D lithography (www. Laser-zentrum-hannover.de)
17. Block copolymer lithography
18. Phase shifting mask (Campbell 7.7)
19. Dual-tone photoresist
20. Focused ion beam (FIB) in fabrication [Geoffrey Schulthess]
21. Ion milling (Campbell 11.5)
22. Atomic layer deposition (ALD) (Campbell 13.9)
23. Semiconductor/metal contacts (Campbell 15.6-15.8)
24. Chemical Mechanical Polishing (CMP) (Campbell 11.2, 15.9-10)
25. Metal CVD (Campbell 13.8)
26. Plasma etch (Campbell 10.5-7, 11.8)
27. MEMS fabrication (Campbell 19.5-19.10 )
28. Carbon Nanotube devices
   CNT-Transistor (Zachary Clark)
   CNT-bolometer (Christian Lange)
29. Graphene devices
30. Fabrication of flexible and stretchable devices (Carter Hansen, Josh Koskan)
31. Microfluid channel fabrication
32. Devices on photonics (Cole miller)
33. Devices on plasmonics